Material Composition Dec © Copyright 2005. IPC, Bannockb electromics industries of international and Pan-American co			burn, Illinois. All rights reserved under both			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
1752-21.1 IPC Web Site for Information on II http://www.ipc.org/IPC-175x				PC-1752 Standard Form Type Distribute			* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ıs Materials ar	ials and Mfg Information				
Supplier	r Informa	tion															
Company name*			Company un	Company unique ID			Unique ID Authority					Response Date*					
onsemi												202	2024-05-17				
Contact Na	ame			Title - Contac	Title - Contact				Phone - Contact*					Email - Contact*			
Product-E	Env-Steward	ds		Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
Authorized	Authorized Representative*			Title - Representative				Phone - Representative*				Em	Email - Representative*				
Product-E	Product-Env-Stewards			Product Enviro Compliance				NA				Pro	Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Item			Number Mfr Item Name				Effective Dat	e Vers	sion	Manufacturing Site		Weig	ght*	UOM	Unit Type		
FAN3224			4CMX-F085 Low-Side Gate Driver SO8				2024-05-17			TH2		80.79	92	mg	Each		
Manufacturing Process Information																	
Terminal Plating / Grid Array Material T			Cerminal Base Alloy J-STD-020 MS			L Rating	Peak Process Body Temperature Max Time at F			e at Peak Tem	ak Temperature Number of Reflow Cycles						
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 3		3		260		C 30		s	econds	3				
Comments																	
ATTENTION: MSL 3 Rated item requires Bake and Dry Pack (after electrical test)																	
For more i	information	regarding material con	nposition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.16	mg	Supplier	Silicon (Si)	7440-21-3		2.16	mg
Die Attach	1.144	mg	Supplier	Ethylene glycol dicyclopentenyl ether methacrylate	68586-19-6		0.04	mg
			Supplier	Bis(a,a-dimethylbenzyl) Peroxide	80-43-3		0.0074	mg
			Supplier	Silver (Ag)	7440-22-4		1.0965	mg
Lead Frame	31.136	mg	Supplier	Zinc (Zn)	7440-66-6		0.0374	mg
			Supplier	Iron (Fe)	7439-89-6		0.7286	mg
			Supplier	Copper (Cu)	7440-50-8		30.3451	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0249	mg
Mold Compound-Black	45.29	mg		Epoxy resin	proprietary data		2.7174	mg
			Supplier	Phenolic Resin	Proprietary Data		2.7174	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2264	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.4965	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.1322	mg
Plating	0.435	mg	Supplier	Palladium (Pd)	7440-05-3		0.0173	mg
			В	Nickel (Ni)	7440-02-0		0.4074	mg
			Supplier	Gold (Au)	7440-57-5		0.0104	mg
Wire Bond - Au	0.627	mg	Supplier	Gold (Au)	7440-57-5		0.627	mg